

Filters
LCR

# CERAMIC CHIP DUPLEXERS

For cordless phone

HHM series

## HHM0140 TYPE

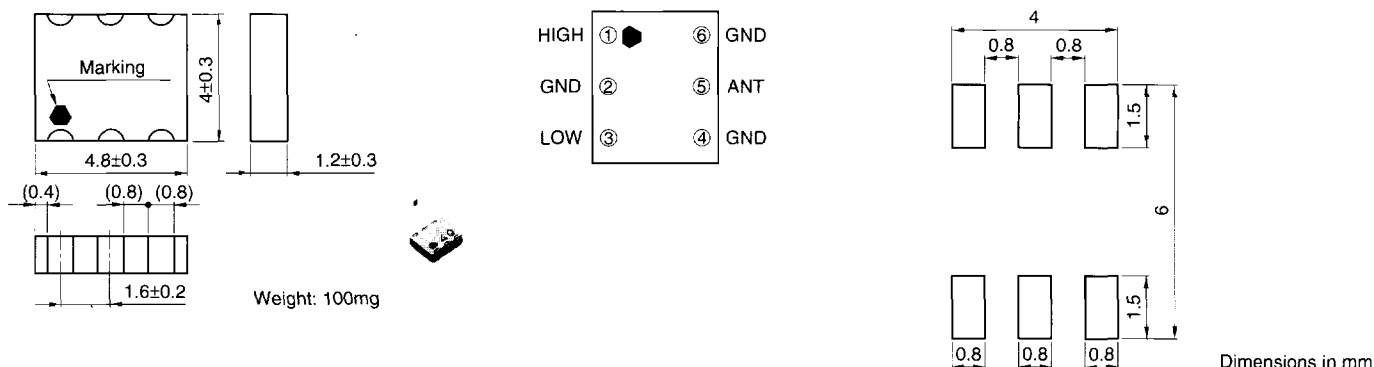
### FEATURES

- HHM series are the multilayer substrate type chip duplexers with built-in LC circuit. That three-dimensionally connects the patterns of each layer at the via-hole conductor and has a multilayer dielectric sheet on which a high definition LC pattern is printed.
- The low pass filter circuit that effectively attenuated high frequency noise from RF amplifiers has been built-in.
- Low impedance GND electrode layer is incorporated on the mounting surface side. Accordingly, combination with the GND pattern of the mother board provides a high attenuation in high frequency band exceeding 1GHz.
- Due to EMI shield effects of this low impedance GND layer, it is difficult to be affected by the circuit pattern on the mother board, and the actual place of installation can be freely set.

### RATINGS

Temperature range	Operating	-10 to +60°C
	Storage	-25 to +85°C
Input/output impedance	50Ω	

### SHAPES AND DIMENSIONS/TERMINAL CONNECTIONS/RECOMMENDED PC BOARD PATTERNS

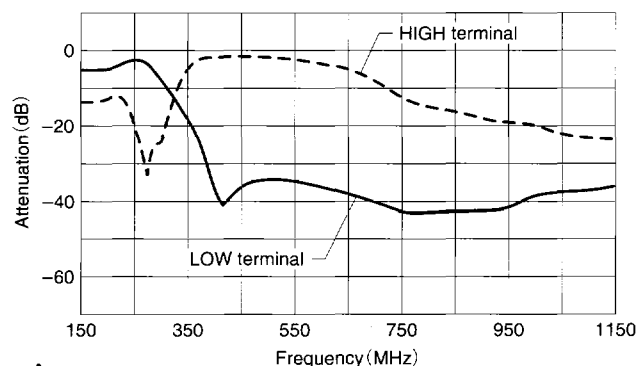


### ELECTRICAL CHARACTERISTICS

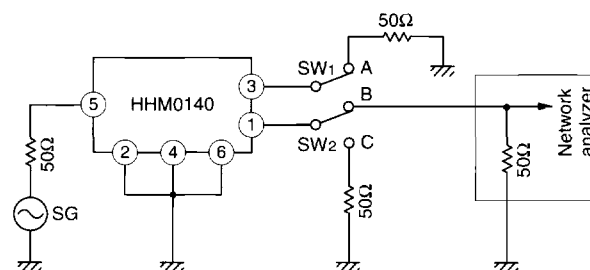
Type	Dimensions (mm) L×W×T	Terminal	Low-pass filter	Insertion loss (dB) max.	Attenuation (dB) min.	Measuring frequency (MHz)	Measuring conditions
HHM0140	4.8×4×1.2	LOW	Built-in	1.8 (1.5 typ.)	—	254	SW1: B SW2: C
				—	20 (25 typ.)	381	
				—	30 (33 typ.)	508	
				—	35 (40 typ.)	762	
		HIGH	—	—	20 (25 typ.)	254	SW1: A SW2: B
				1.7 (1.4 typ.)	—	381	

### TYPICAL ELECTRICAL CHARACTERISTICS

#### ATTENUATION vs. FREQUENCY CHARACTERISTICS



#### MEASURING CIRCUITS



Specifications which provide more details for the proper and safe use of the described product are available upon request.

All specifications are subject to change without notice.